

P-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)	Q _g (Typ.)	
- 100	0.100 at V _{GS} = - 10 V	- 16	11.7	
- 100	0.120 at V_{GS} = - 4.5 V	- 15	11.7	

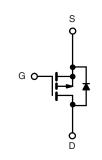
TO-251

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Power Switch
- DC/DC Converters



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T_{C} = 25 °C, unless otherwise noted					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	- 100	N/		
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C	1-	- 16		
	T _C = 70 °C	۱ _D	- 14		
Pulsed Drain Current		I _{DM}	- 50	A	
Avalanche Current		I _{AS}	- 18		
Single Avalanche Energy ^a L = 0.1 mH		E _{AS}	16.2	mJ	
Maximum Power Dissipation ^a	T _C = 25 °C		32.1 ^b	w	
	T _A = 25 °C ^c	- P _D -	2.5		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	50	°C/W		
Junction-to-Case (Drain)	R _{thJC}	3.9	0/10		

Notes:

a. Duty cycle ≤ 1 %.

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).



COMPLIANT HALOGEN

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V_{DS} $V_{DS} = 0 V, I_D = -250 \mu A$ - 100				- v	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1	- 1 - 2.5			
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 250	nA	
		$V_{DS} = -100 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	- 1 - 50 μΑ - 250	
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = - 100 V, V_{GS} = 0 V, T_{J} = 125 °C			- 50		
		V_{DS} = - 100 V, V_{GS} = 0 V, T_{J} = 150 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le$ - 10 V, V_{GS} = - 10 V	- 15			Α	
	D	V _{GS} = - 10 V, I _D = - 3.6 A		0.100		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 3.4 A		0.120			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 3.6 A		12		S	
Dynamic ^b		· · · ·					
Input Capacitance	C _{iss}			1055		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = - 50 V, f = 1 MHz		65			
Reverse Transfer Capacitance	C _{rss}	1		41			
Tatal Oata Oharma ⁶		$V_{DS} = -50 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -3.6 \text{ A}$		23.2	34.8	nC	
Total Gate Charge ^c	Q _g			11.7	17.6		
Gate-Source Charge ^c	Q _{gs}	V_{DS} = - 50 V, V_{GS} = - 4.5 V, I_{D} = - 3.6 A		3.5			
Gate-Drain Charge ^c	Q _{gd}			4.8			
Gate Resistance	Rg	f = 1 MHz	1.2	5.7	11.5	Ω	
Turn-On Delay Time ^c	t _{d(on)}			7	14		
Rise Time ^c	t _r	V_{DD} = - 50 V, R_L = 17.2 Ω		12	18	nc	
Turn-Off Delay Time ^c	t _{d(off)}	$I_{D}\cong$ - 2.9 A, V_{GEN} = - 10 V, R_{g} = 1 Ω		33	50	- ns	
Fall Time ^c	t _f			9	18		
Drain-Source Body Diode Ratings and	nd Characteri	stics T _C = 25 °C ^b					
Continuous Current	ا _S				- 8.8	^	
Pulsed Current	I _{SM}				- 15	A	
Forward Voltage ^a	V _{SD}	$I_{F} = -2.9 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.8	- 1.5	V	
Reverse Recovery Time	t _{rr}			50	75	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 2.9 A, dl/dt = 100 A/μs		- 4	- 6	Α	
Reverse Recovery Charge	Q _{rr}	1 1		98	147	nC	

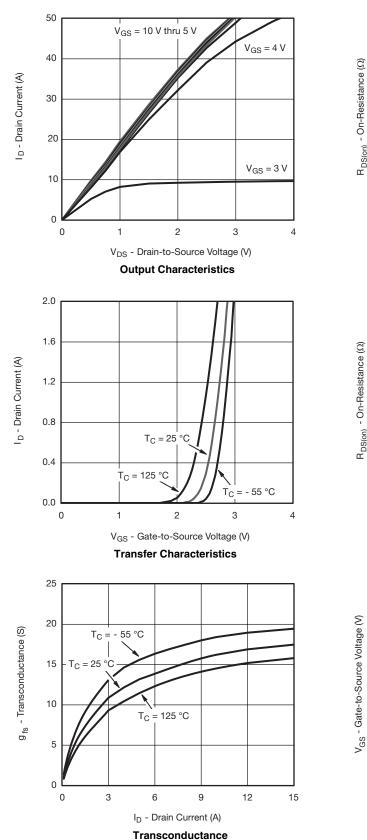
Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

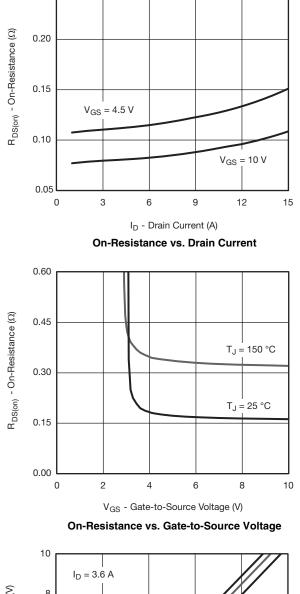
b. Guaranteed by design, not subject to production testing.c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

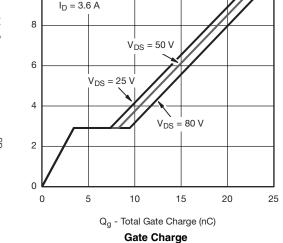




TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

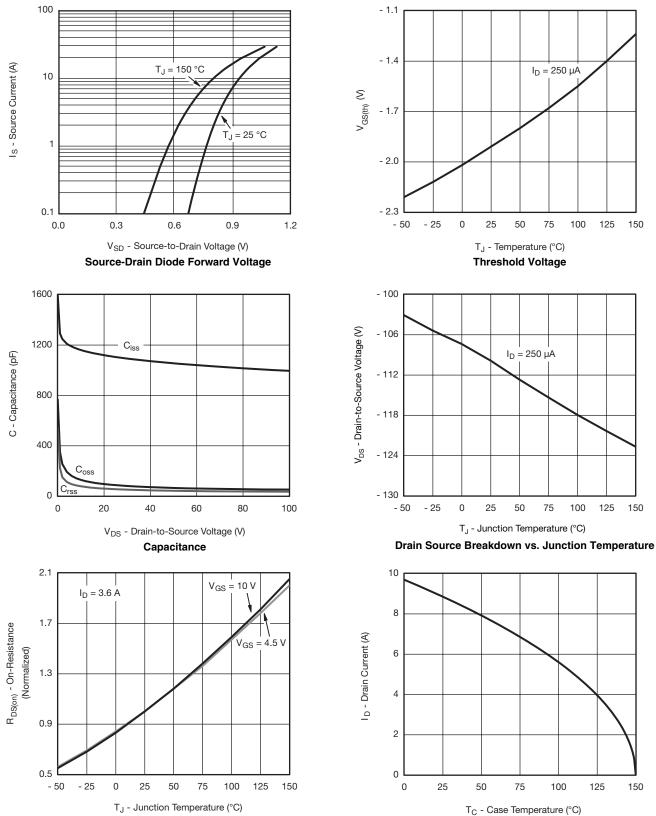


0.25





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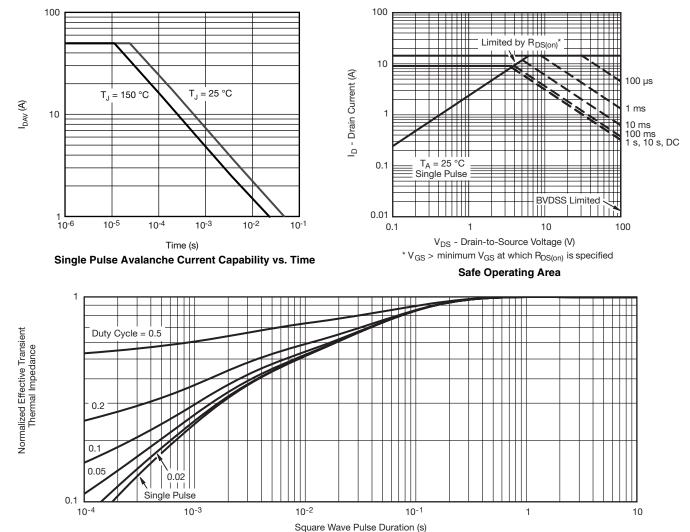


On-Resistance vs. Junction Temperature

Current Derating



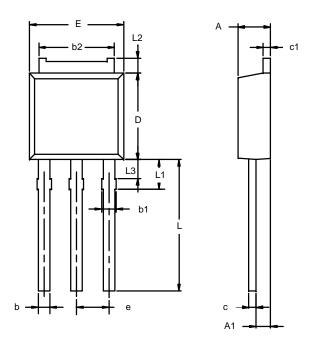
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Case



TO-251AA



	MILLIMETERS		INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
c1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	

Note: Dimension L3 is for reference only.



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